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Operators Manual

Centering Device

Cost Effective Equipment

Contents

1. Introduction

1.1. Confidentiality Statement

Information supplied is for the use in the operation and/or maintenance of Cee equipment.
Neither this document nor the information it contains shall be disclosed to others for manufacturing or any other purpose without written authorization from, Cost Effective Equipment, LLC.

2. Centering Device Use

The handheld centering device can be used for specific sizes and is very cost-effective. This component will positively mate to the side of a specific chuck and allow for quick alignment of the referenced size. Handheld devices are available for 2 inch and 3 inch, 100 mm, 125 mm, 150 mm, 200 mm, and 300 mm sizes.

2.1. Choosing a Chuck for the Substrate

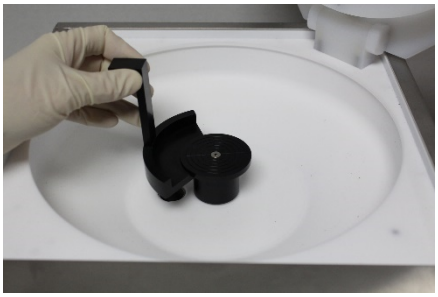
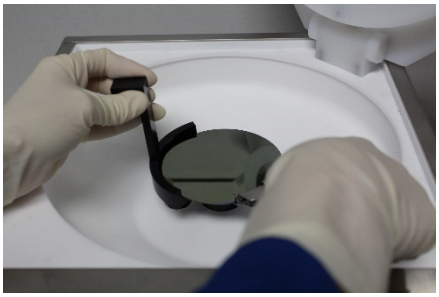
Handheld centering devices are specifically designed for wafer diameter and chuck diameter. The chart below shows the available options. Custom options are also available.

Cee® Available Centering Device

Wafer Diameter	Chuck Size
2 inch	1 inch
3 inch	2.25 inch
100 mm	2.25 inch
125 mm	4 inch
150 mm	4 inch
200 mm	4 inch
200 mm	6.188 inch
300 mm	6.188 inch

2.2. Centering Device Procedure

1. First, identify the specific hand-held center fixture that is compatible with the appropriately sized spin chuck and wafer diameter.
2. Next, open the spin lid and position the centering device into positive contact with the outer radius of the spin chuck.
3. Then, place the substrate onto the spin chuck with wafer tweezers, vacuum wand or manually by hand.
4. Next, gently apply pressure to the outer edge of the substrate until opposing edge is secure against the vertical radial wall of the centering device.
5. Next, press the vacuum on button on the run process screen and confirm substrate is present status.
6. Then, move the hand-held device away from the substrate and out of the spin bowl chamber.
7. Finally, you're ready to close the lid and start the spin program.


3. Preventative Maintenance

This maintenance manual provides personnel with procedure and guidelines for maintaining a Cee® centering. Below is a chart of recommend maintenance scheduling.

Maintenance Section	Maintenance Schedule
Safety Checks	Before daily tool use
Cleaning	After daily tool use
Mechanical Checklist	See Section Below Details

3.1. Safety Checks

Inspect spin chuck lid for the following defects:

(a) Loose assemblies
(b) Damage to the surface
(c) Dirty surface

3.2. Mechanical Checklist

1. **Centering Device cleanliness:** If any material has built up on the centering device, it can be wiped clean with most organic solvents isopropyl alcohol, or acetone. For major buildup of material, a glass slide can be used to gently scrap the material away. Follow by wiping clean. A dirty centering device could cause contamination of wafers. See section below on detailed cleaning instructions. **Daily**

3.3. Cleaning

For cleaning, it is good practice to use the mildest solvent possible: organic solvents, acetone, isopropyl alcohol, or N-methylpyrrolidinone (NMP). Caustic acids or bases should not be used.